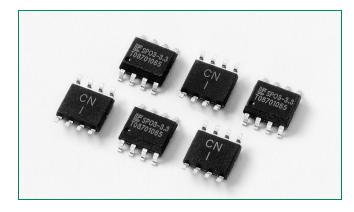
# SP03-3.3 Series 3.3V 150A Diode Array







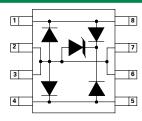




## **Agency Approvals - Pending**

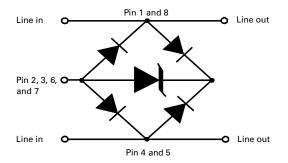
Agency	Agency File Number
<b>71</b>	E128662

#### **Pinout**



SOIC-8 (Top View)

#### **Functional Block Diagram**



## Additional Information









Samples

Life Support Note:

#### Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

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Specifications are subject to change without notice

Revised: 11/22/16

### **Description**

This new broadband protection device from Littelfuse provides overvoltage protection for applications such as 10/100/1000 BaseT Ethernet, T3/E3 DS3 interfaces, ADSL2+, and VDSL2+. This new protector combines the TVS diode element with a diode rectifier bridge to provide both longitudinal and differential protection in one package. This design innovation results in a capacitive loading characteristic that is log-linear with respect to the signal voltage across the device. This reduces intermodulation (IM) distortion caused by a typical solid-state protection solution. The application schematic provides the connection information.

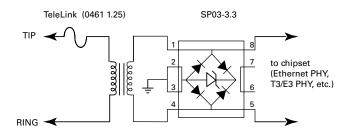
#### **Features**

- RoHS compliant
- SOIC-8 surface mount package (JEDEC MS-012)
- Low insertion loss, loglinear capacitance
- Combined longitudinal and metallic protection
- Lightning Protection, IEC 61000-4-5, 100A (8/20µs)
- · Clamping speed of nanoseconds
- UL 94V-0 epoxy molding
- UL recognized component
- Low clamping voltage
- Lead-free

### **Applications**

- T1/E1 Line cards
- T3/E3 and DS3 Interfaces
- STS-1 Interfaces
- 10/100/1000 BaseT Ethernet

#### Application Example



This schematic shows a high-speed data interface protection solution. The SP03-3.3 provides both metallic (differential) and longitudinal (common mode) protection from lightning induced surge events. Its surge rating is compatible with the intra-building surge requirements of Telcordia's GR-1089-CORE, and the Basic Level Recommendations of ITU K.20 and .21. This device protects against both positive and negative induced surge events. The TeleLink fuse provides overcurrent protection for the long term 50/60 Hz power fault events.



Absolute Maximum Ratings				
Parameter	Rating	Units		
Peak Pulse Current (8/20µs)	150	А		
Peak Pulse Power (8/20µs)	3300	W		
IEC 61000-4-2, Direct Discharge, (Level 4)	30	kV		
IEC 61000-4-2, Air Discharge, (Level 4)	30	kV		
IEC 61000-4-5 (8/20μs)	100	А		
Telcordia GR 1089 (Intra-Building) (2/10µs)	100	А		
ITU K.20 (5/310µs)	40	А		

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Thermal Information				
Parameter	Rating	Units		
SOIC Package	170	°C/W		
Operating Temperature Range	-40 to 125	°C		
Storage Temperature Range	-55 to 150	°C		
Maximum Junction Temperature	150	°C		
Maximum Lead Temperature (Soldering 20-40s) (SOIC - Lead Tips Only)	260	°C		

## **Electrical Characteristics (T<sub>OP</sub> = 25°C)**

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Reverse Stand-Off Voltage	V <sub>RWM</sub>	-	-	-	3.3	V
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>T</sub> = 2μΑ	3.3	-	-	V
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>T</sub> = 50μA	3.3	-	-	V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> = 3.3V, T= 25°C	-	-	1	μА
Clamping Voltage, Line-Ground	V <sub>C</sub>	I <sub>PP</sub> = 50A, t <sub>p</sub> =8/20 μs	-	-	11.5	V
Clamping Voltage, Line-Ground	V <sub>C</sub>	I <sub>PP</sub> = 100A, t <sub>p</sub> =8/20 μs	-	-	15	V
Clamping Voltage, Line-Line	V <sub>C</sub>	I <sub>PP</sub> = 50A, t <sub>p</sub> =8/20 μs	-	-	13.5	V
Clamping Voltage, Line-Line	V <sub>C</sub>	I <sub>PP</sub> = 100A, t <sub>p</sub> =8/20 μs	-	-	18	V
Lunation Consoltance		Between I/O Pins and Ground $V_R=0V$ , $f=1MHz$	-	16	25	pF
Junction Capacitance	C <sub>j</sub>	Between I/O Pins V <sub>R</sub> =0V, f= 1MHz	-	8	12	pF

Figure 1: Non-repetitive Peak Pulse Current vs. Pulse Time



**Figure 2: Current Derating Curve** 

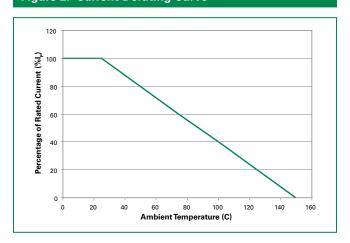




Figure 3: Pulse Waveform

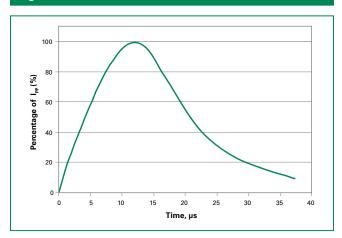


Figure 4: Clamping Voltage vs. Peak Pulse Current

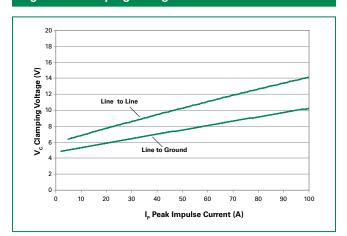


Figure 5: Capacitance vs. Reverse Voltage

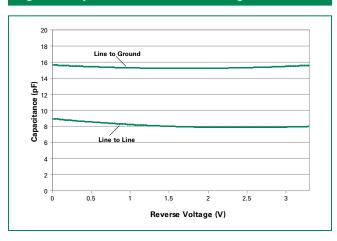
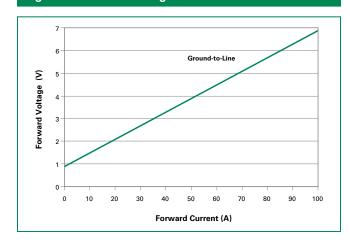
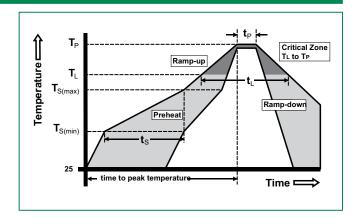


Figure 6: Forward Voltage vs. Forward Current



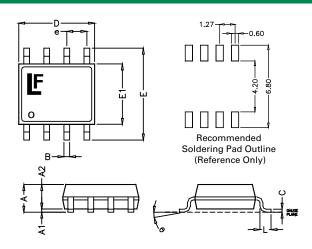
## **Soldering Parameters**

Reflow Condition		Pb – Free assembly	
	-Temperature Min (T <sub>s(min)</sub> )	150°C	
Pre Heat	-Temperature Max (T <sub>s(max)</sub> )	200°C	
	-Time (min to max) (t <sub>s</sub> )	60 – 180 secs	
Average ramp up rate (Liquidus) Temp (T <sub>L</sub> ) to peak		3°C/second max	
T <sub>S(max)</sub> to T <sub>L</sub> - Ramp-up Rate		3°C/second max	
Reflow	-Temperature (T <sub>L</sub> ) (Liquidus)	217°C	
nellow	-Temperature (t <sub>L</sub> )	60 – 150 seconds	
PeakTemperature (T <sub>P</sub> )		260+0/-5 °C	
Time within 5°C of actual peak Temperature (t <sub>p</sub> )		20 – 40 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T <sub>P</sub> )		8 minutes Max.	
Do not exceed		260°C	



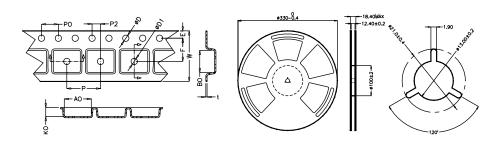


## Package Dimensions — Mechanical Drawings and Recommended Solder Pad Outline



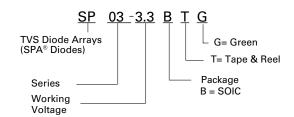
Package	SOIC-8			
Pins	8			
JEDEC	MS-012			
	Millimetres Inches			nes
	Min	Max	Min	Max
Α	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
A2	1.25	1.65	0.050	0.065
В	0.31	0.51	0.012	0.020
C	0.17	0.25	0.007	0.010
D	4.80	5.00	0.189	0.197
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
е	1.27 BSC 0.050 BSC			BSC
L	0.40	1.27	0.016	0.050

## **Embossed Carrier Tape & Reel Specification — SOIC Package**



	Millimetres		Ind	ches
	Min	Max	Min	Max
E	1.65	1.85	0.065	0.073
F	5.4	5.6	0.213	0.22
P2	1.95	2.05	0.077	0.081
D	1.5	1.6	0.059	0.063
D1	1.50 Min		0.059 Min	
P0	3.9	4.1	0.154	0.161
10P0	40.0 ± 0.20		1.574 ± 0.008	
W	11.9	12.1	0.468	0.476
P	7.9	8.1	0.311	0.319
A0	6.3	6.5	0.248	0.256
B0	5.1	5.3	0.2	0.209
K0	2	2.2	0.079	0.087
t	t 0.30 ± 0.05		0.012	± 0.002

## **Part Numbering System**



## **Part Marking System**



## **Ordering Information**

Part Number	Package	Marking	Min. Order Qty.
SP03-3.3BTG	SOIC Tape & Reel	SP03-3.3	2500

## **Product Characteristics**

Lead Plating	Matte Tin
Lead Material	Copper Alloy
Lead Coplanarity	0.004 inches (0.102mm)
Substitute Material	Silicon
Body Material	Molded Epoxy
Flammability	UL 94 V-0

- All dimensions are in millimeters
  Dimensions include solder plating.
  Dimensions are exclusive of mold flash & metal burr.
- Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
  Package surface matte finish VDI 11-13.